

This listing of claims replaces all prior versions, and listings of claims in the instant application:

Listing of Claims:

1. (Original) An image sensor package comprising:
an image sensor die comprising an approximately or completely planar photosensing surface which receives external light and converts the received light into an electrical signal, a plurality of bond pads at the peripheral side of the photosensing surface, and an approximately or completely planar non-photosensing surface on the side opposite to the photosensing surface and the bond pads;

a substrate comprising an insulating layer comprising an approximately or completely planar first surface to which the non-photosensing surface of the image sensor die is adhered by an adhesive and an approximately or completely planar second surface on the opposite side thereof, a plurality of electrically conductive patterns being formed on each of the first and second surfaces;

a plurality of conductive wires electrically connecting the bond pads of the image sensor die to the electrically conductive patterns on the first surface of the insulating layer;

a support wall on the first surface of the insulating layer of the substrate around the periphery of the conductive wires and comprising a plurality of screw threads on the outer peripheral surface thereof; and

a mount comprising an aperture into which a barrel comprising a plurality of lenses is mounted.

2. (Original) The image sensor package as claimed in claim 1, wherein at least one passive element is further

provided on the substrate at the outer peripheral side of the support wall.

3. (Original) The image sensor package as claimed in claim 1, wherein the barrel further includes an infrared blocking glass disposed below the plurality of lenses.

4. (Original) The image sensor package as claimed in claim 1, wherein a flexible circuit is connected to the electrically conductive patterns formed on the second surface of the insulating layer of the substrate.

5-24. (Canceled)

25. (Previously presented) The image sensor package as claimed in claim 1 wherein the mount comprises a plurality of screw threads on the outer peripheral surface of the mount.

26. (Previously presented) The image sensor package as claimed in claim 25 wherein the screw threads of the mount are engaged with the screw threads of the support wall.

27. (Previously presented) The image sensor package as claimed in claim 26 wherein a distance between the barrel and the image sensor die is adjusted by turning the mount.

28. (Canceled)

29. (New) An image sensor package comprising:
an image sensor die comprising:
a photosensing surface;
a plurality of bond pads at the photosensing surface;
and

a non-photosensing surface on the side opposite to the photosensing surface;

a substrate comprising:

an insulating layer comprising a first surface and a second surface, the non-photosensing surface of the image sensor die being coupled to the first surface of the insulating layer; and

a plurality of electrically conductive patterns being formed on each of the first and second surfaces;

a plurality of conductive wires electrically connecting the bond pads of the image sensor die to the electrically conductive patterns on the first surface of the insulating layer;

a support wall on the first surface of the insulating layer of the substrate around the periphery of the conductive wires and comprising a plurality of screw threads on the outer peripheral surface thereof;

a mount coupled to the screw threads of the support wall, the mount comprising an aperture; and

a barrel mounted into the aperture of the mount, the barrel comprising at least one lens.

30. (New) The image sensor package as claimed in claim 29, wherein at least one passive element is further provided on the substrate at the outer peripheral side of the support wall.

31. (New) The image sensor package as claimed in claim 29, wherein the barrel further includes an infrared blocking glass disposed below the at least one lens.

32. (New) The image sensor package as claimed in claim 29 further comprising a flexible circuit connected to the electrically conductive patterns formed on the second surface of the insulating layer of the substrate.

33. (New) The image sensor package as claimed in claim 29 wherein the mount comprises a plurality of screw threads on the outer peripheral surface of the mount.

34. (New) The image sensor package as claimed in claim 33 wherein the screw threads of the mount are engaged with the screw threads of the support wall.

35. (New) The image sensor package as claimed in claim 34 wherein a distance between the barrel and the image sensor die is adjusted by turning the mount.

36. (New) The image sensor package as claimed in claim 29 wherein the substrate further comprises vias connecting the electrically conductive patterns formed on the first and second surfaces of the insulating layer.

37. (New) The image sensor package as claimed in claim 29 wherein the electrically conductive patterns formed on the second surface of the insulating layer comprise ball lands.

38. (New) The image sensor package as claimed in claim 37 further comprising solders on the ball lands.

39. (New) The image sensor package as claimed in claim 38 further comprising a flexible circuit connected to the ball lands by the solders.

40. (New) The image sensor package as claimed in claim 39 wherein the flexible circuit is for connection of the image sensor package to an external device.

41. (New) An image sensor package comprising:

an image sensor die comprising:

a photosensing surface;

a plurality of bond pads at the photosensing surface; and

a non-photosensing surface on the side opposite to the photosensing surface;

a substrate comprising:

an insulating layer comprising a first surface and a second surface, the non-photosensing surface of the image sensor die being coupled to the first surface of the insulating layer;

a plurality of electrically conductive patterns being formed on the first surface; and

a plurality of electrically conductive patterns comprising ball lands being formed on the second surface;

a plurality of conductive wires electrically connecting the bond pads of the image sensor die to the electrically conductive patterns on the first surface of the insulating layer;

a support wall on the first surface of the insulating layer of the substrate around the periphery of the conductive wires and comprising a plurality of screw threads on the outer peripheral surface thereof;

a mount coupled to the screw threads of the support wall, the mount comprising an aperture;

a barrel mounted into the aperture of the mount, the barrel comprising at least one lens;

at least one passive element provided on the substrate at the outer peripheral side of the support wall; and

a flexible circuit connected to the ball lands by solders, the flexible circuit for connection of the image sensor package to an external device.